



FireDAQ for FLAME – architecture and hardware considerations

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- New readout scheme
 - New Trenz Electronic module with Zynq UltraScale+
- FPGA firmware details
- System bandwidth (maximal event rate)
- Work to be done (and by whom...)

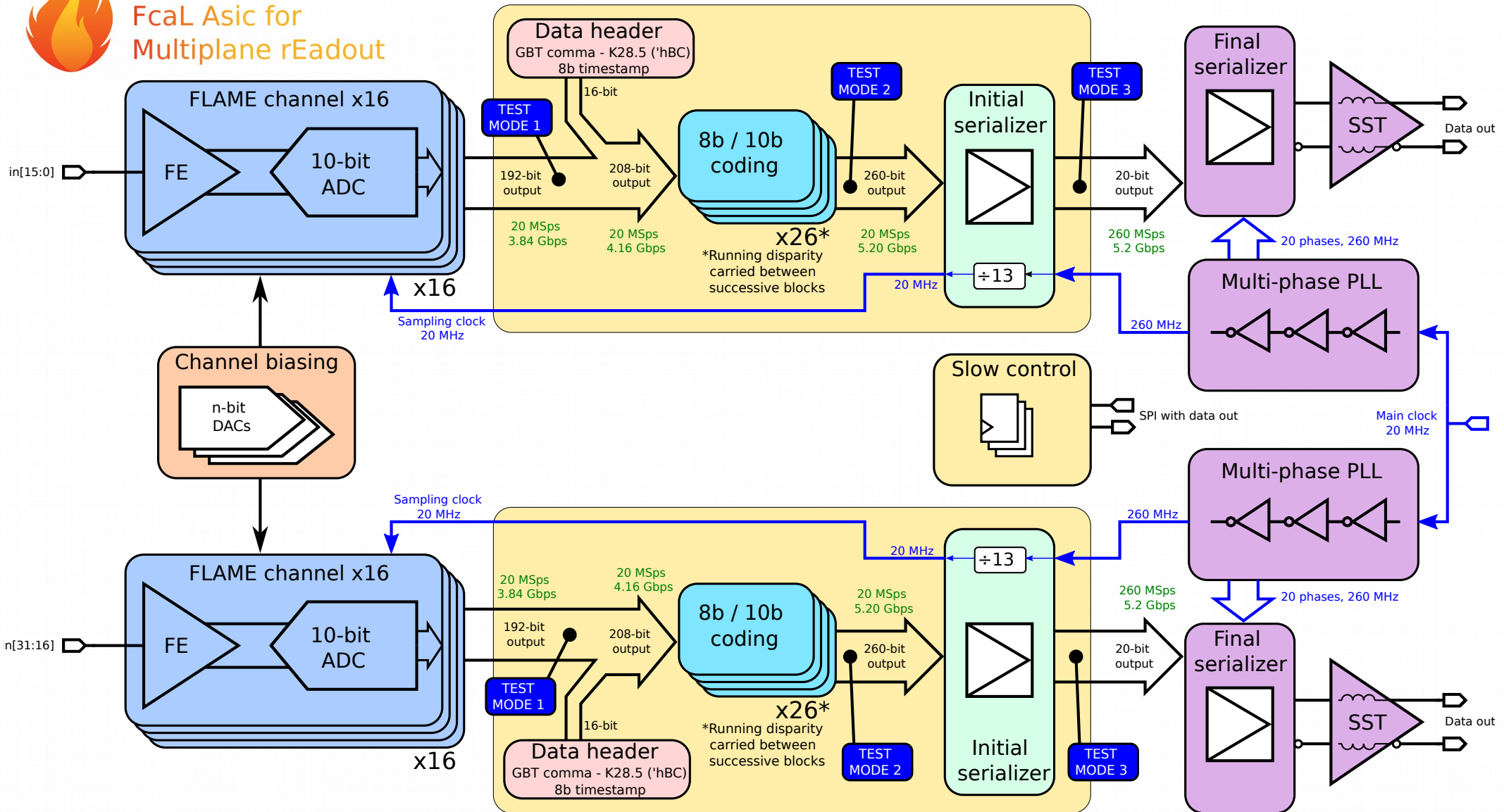
FLAME ASIC architecture

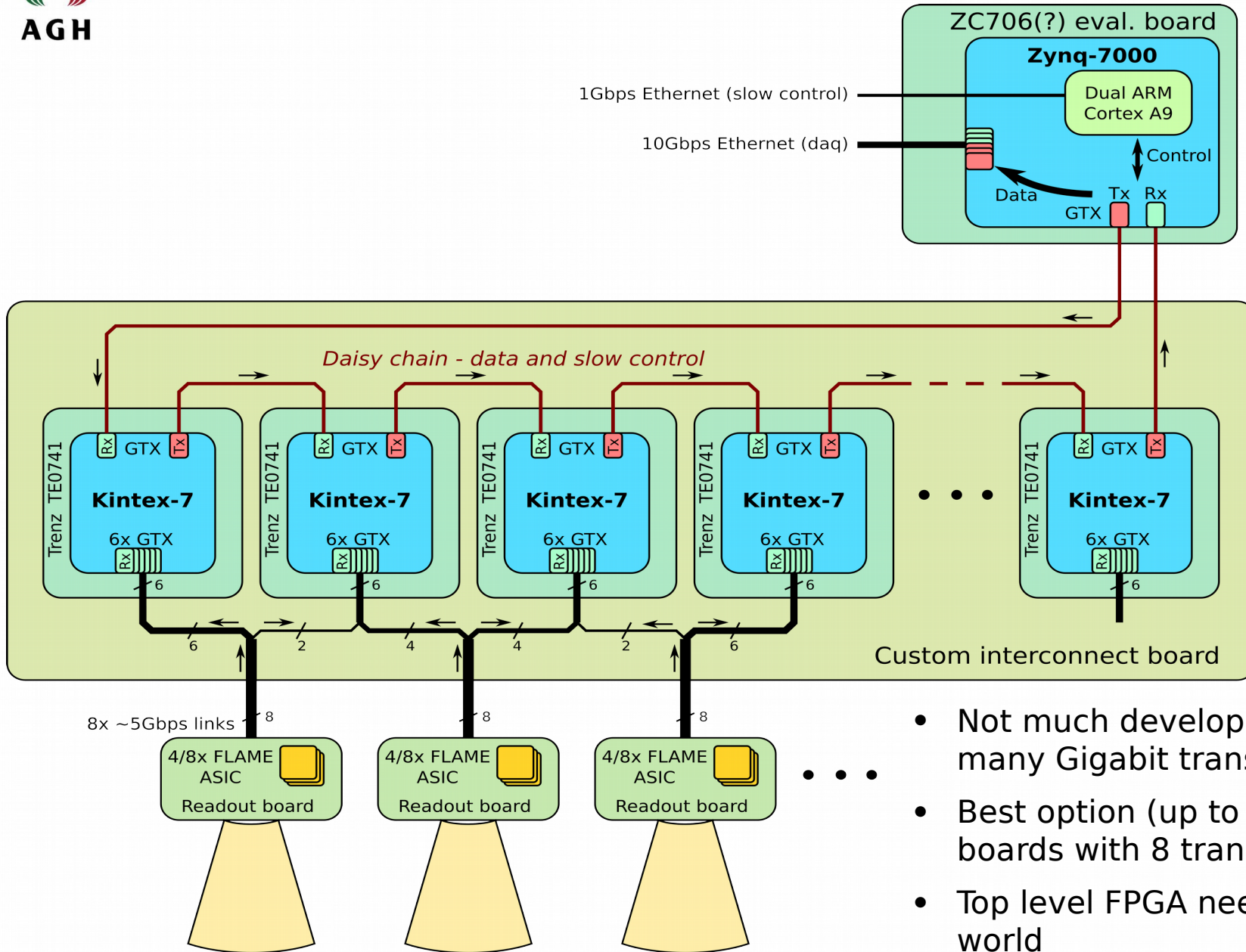


FLAME

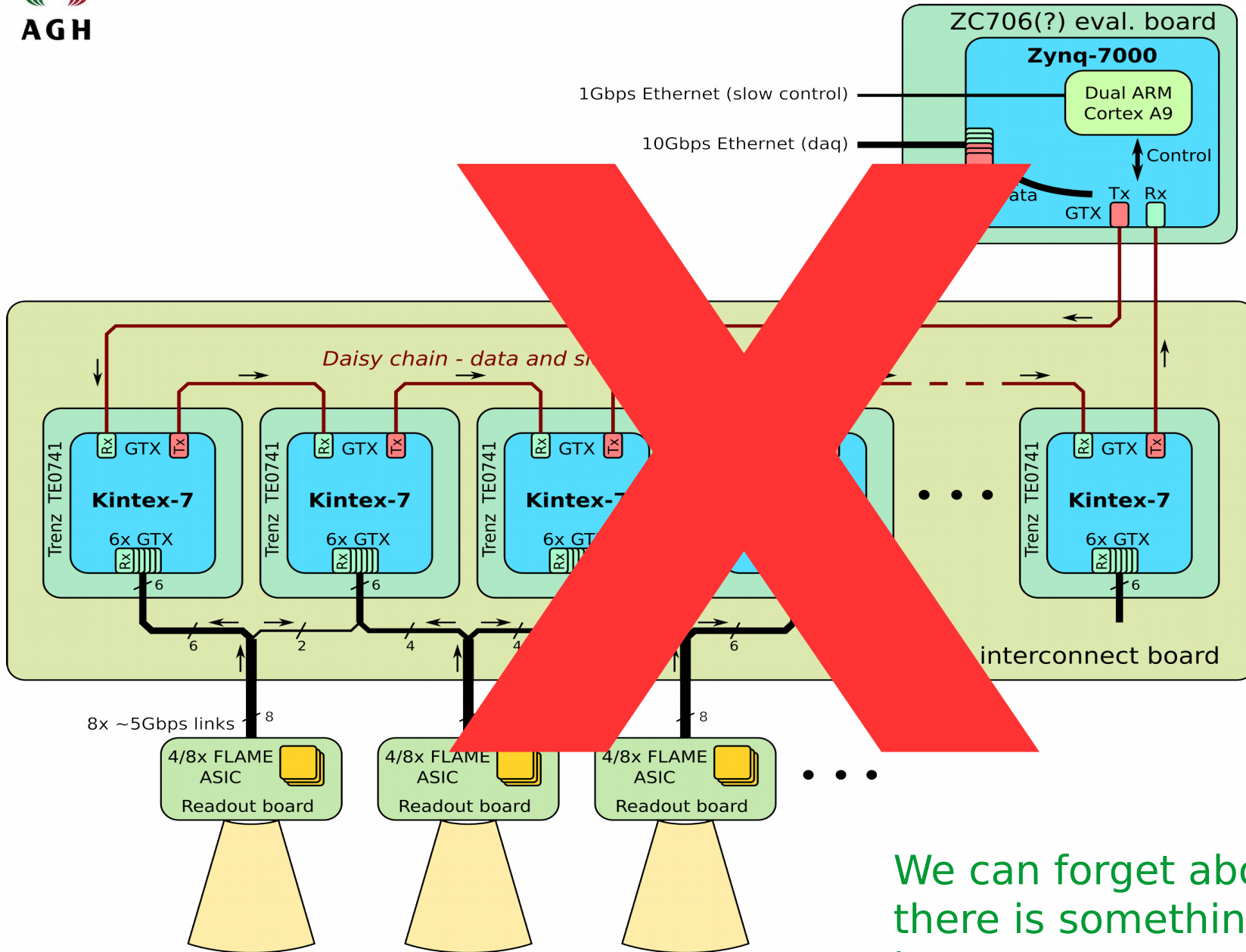
FcaL Asic for
Multiplane rEadout

- Two 16-channel, fully functional blocks → two “ASICs” in one padding to save the PCB area and maximize the instrumented sensor area





- Not much development boards with many Gigabit transceivers available...
- Best option (up to now) - Trenz Electronic boards with 8 transceivers
- Top level FPGA needed as port to outside world
- **Very complicated scheme...**



We can forget about this scheme, there is something definitely better!

Trenz Electronic TE0808 modules



€999.00 (1,188.81 € gross) *

Prices plus VAT plus shipping costs

● expected to be available on 24-Nov-2018

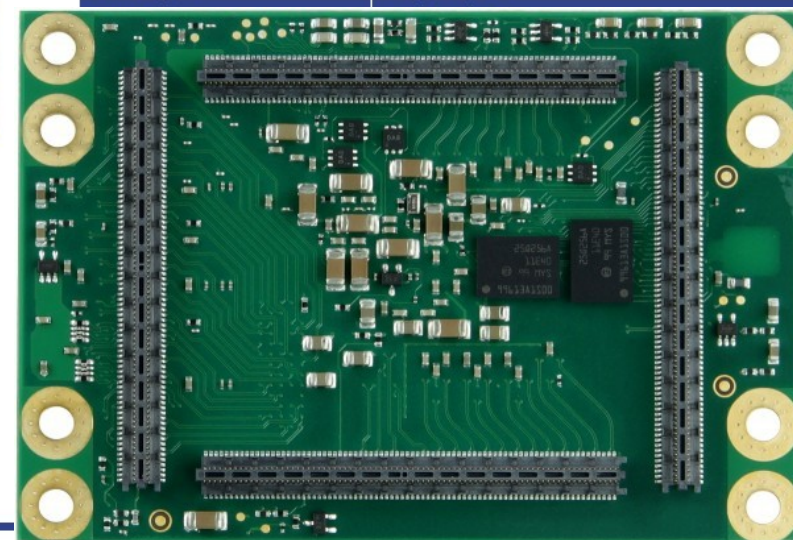
1

Add to shopping cart

Remember

Order number: TE0808-04-09EG-1EE

In Stock: 0



Description

Downloads

Resources

Product information "UltraSOM+ MPSoC Module with Zynq UltraScale+ XCZU9EG-1FFVC900E, 4 GB DDR4"

The Trenz Electronic TE0808-04-09EG-1EE is a MPSoC module integrating a Xilinx Zynq UltraScale+ ZU9EG, 4 GByte DDR4 SDRAM with 64-Bit width, 128 MByte Flash memory for configuration and operation, 20 Gigabit transceivers, and powerful switch-mode power supplies for all on-board voltages. A large number of configurable I/O's is provided via rugged high-speed stacking connections.

All parts are at least extended temperature range of 0°C to +85°C. The module operating temperature range depends on customer design and cooling solution. Please contact us for options.

All this on a tiny footprint of 5.2 x 7.6 cm at the most competitive price. These high-density integrated modules are smaller than a credit card and available in several variants.

Slightly shorter than the credit card

We are trying to buy two TE0808-04-09EG modules just now

Trenz board	FPGA	Price (EUR with tax)	System cells	CLB flip-flops	CLK LUTs	DSP slices	DDR4 RAM
TE0808-04-06EG-1EE	XCZU6EG-1FFVC900E	1070	469k	429k	215k	1973	4 GB
TE0808-04-09EG-1EE	XCZU9EG-1FFVC900E	1189	600k	548k	274k	2520	4 GB
TE0808-04-15EG-1EE	XCZU15EG-1FFVC900E	1605	747k	682k	341k	3528	2 GB

€899.00 (1,069.81 € gross) *

Prices plus VAT plus shipping costs

● expected to be available on 29-Nov-2018

1

♥ Remember

Order number: TE0808-04-06EG-1EE

In Stock: 0

Quantity	Unit price
To 9	€899.00 (1,069.81 € gross) *
From 10	€809.10 (962.83 € gross) *
From 25	€791.12 (941.43 € gross) *
From 50	€764.15 (909.34 € gross) *
From 100	€737.18 (877.24 € gross) *
From 250	€719.20 (855.85 € gross) *
From 500	€674.25 (802.36 € gross) *
From 1000	€629.30 (748.87 € gross) *

€999.00 (1,188.81 € gross) *

Prices plus VAT plus shipping costs

● Ready to ship today.
Delivery time appr. 1-3 workdays

1

♥ Remember

Order number: TE0808-04-09EG-1EE

In Stock: 7

Quantity	Unit price
To 9	€999.00 (1,188.81 € gross) *
From 10	€899.10 (1,069.93 € gross) *
From 25	€879.12 (1,046.15 € gross) *
From 50	€849.15 (1,010.49 € gross) *
From 100	€819.18 (974.82 € gross) *
From 250	€799.20 (951.05 € gross) *
From 500	€749.25 (891.61 € gross) *
From 1000	€699.30 (832.17 € gross) *

€1,349.00 (1,605.31 € gross) *

Prices plus VAT plus shipping costs

● expected to be available on 31-Jan-2019

1

♥ Remember

Order number: TE0808-04-15EG-1EE

In Stock: 0

Quantity	Unit price
To 9	€1,349.00 (1,605.31 € gross) *
From 10	€1,214.10 (1,444.78 € gross) *
From 25	€1,146.65 (1,364.51 € gross) *
From 50	€1,079.20 (1,284.25 € gross) *
From 100	€1,011.75 (1,203.98 € gross) *
From 250	€944.30 (1,123.72 € gross) *
From 500	€876.85 (1,043.45 € gross) *
From 1000	€809.40 (963.19 € gross) *

UltraITX+ Baseboard for Trenz Electronic TE080X UltraSOM+

This could be very helpful, we are trying to buy one just now



€799.00 (950.81 € gross) *

Prices plus VAT plus shipping costs

● expected to be available on 07-Dec-2018

1

♥ Remember

Order number: TEBF0808-04

In Stock: 0

Quantity	Unit price
To 9	€799.00 (950.81 € gross) *
From 10	€719.10 (855.73 € gross) *
From 25	€679.15 (808.19 € gross) *
From 50	€639.20 (760.65 € gross) *
From 100	€599.25 (713.11 € gross) *
From 250	€559.30 (665.57 € gross) *
From 500	€519.35 (618.03 € gross) *
From 1000	€479.40 (570.49 € gross) *

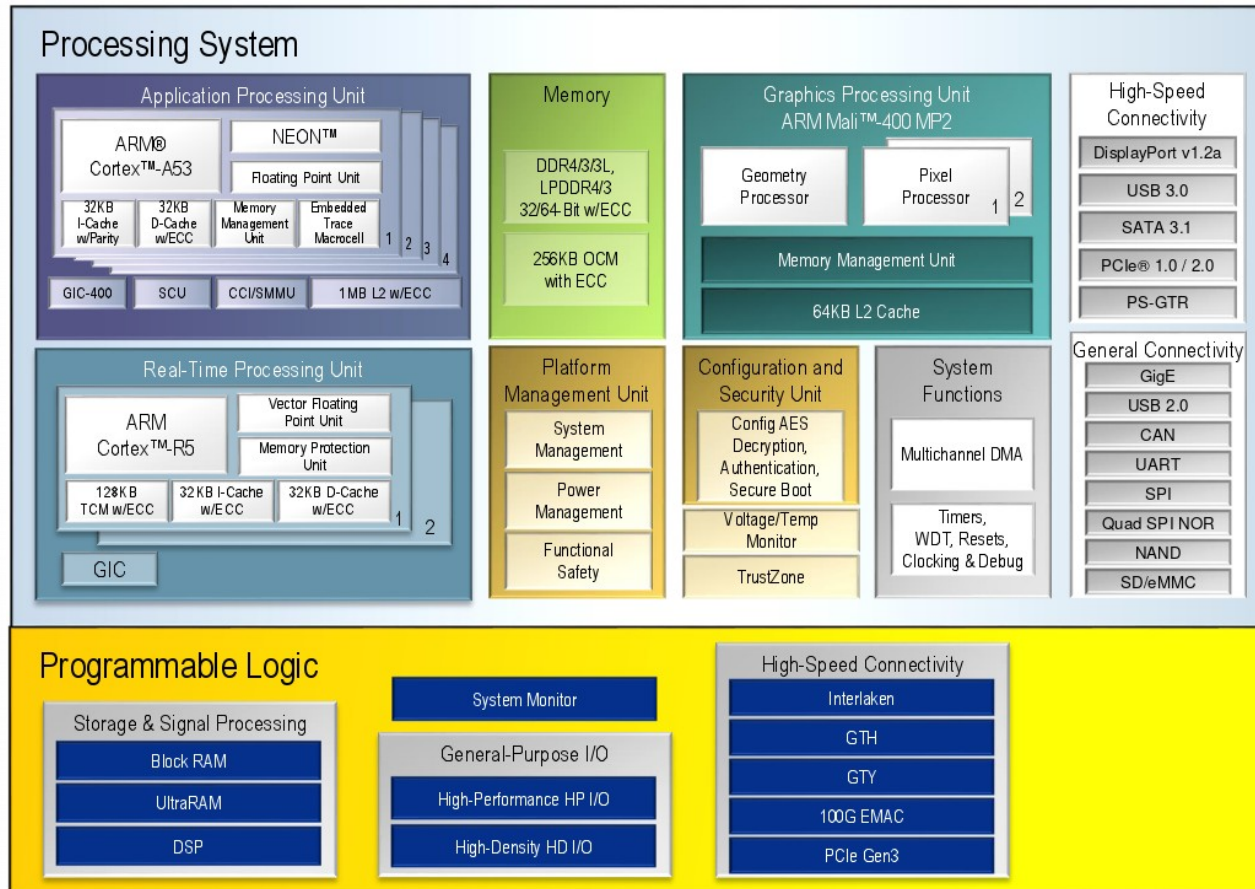
Description

Downloads

Resources

Product information "UltraITX+ Baseboard for Trenz Electronic TE080X UltraSOM+"

The Trenz Electronic TEBF0808 carrier board is a baseboard for the Xilinx Zynq Ultrascale+ MPSoC modules TE0803, TE0807 und TE0808, which exposes the module's B2B connector pins to accessible connectors and provides a whole range of on-board components to test and evaluate the Zynq Ultrascale+ SoMs and for developing purposes. The carrier board has a Mini-ITX form factor making it capable to be fitted into a PC enclosure. On the PC enclosure's rear and front panel, MGT interfaces and connectors are accessible, for the front panel elements there are also Intel-PC compatible headers available.



CG Devices

EG Devices

EV Devices

	CG Devices	EG Devices	EV Devices
Application Processor	Dual-core ARM® Cortex™-A53 MPCore™ up to 1.3GHz	Quad-core ARM Cortex-A53 MPCore up to 1.5GHz	Quad-core ARM Cortex-A53 MPCore up to 1.5GHz
Real-Time Processor	Dual-core ARM Cortex-R5 MPCore up to 533MHz	Dual-core ARM Cortex-R5 MPCore up to 600MHz	Dual-core ARM Cortex-R5 MPCore up to 600MHz
Graphics Processor		Mali™-400 MP2	Mali™-400 MP2
Video Codec			H.264 / H.265
Programmable Logic	103K–600K System Logic Cells	103K–1143K System Logic Cells	192K–504K System Logic Cells

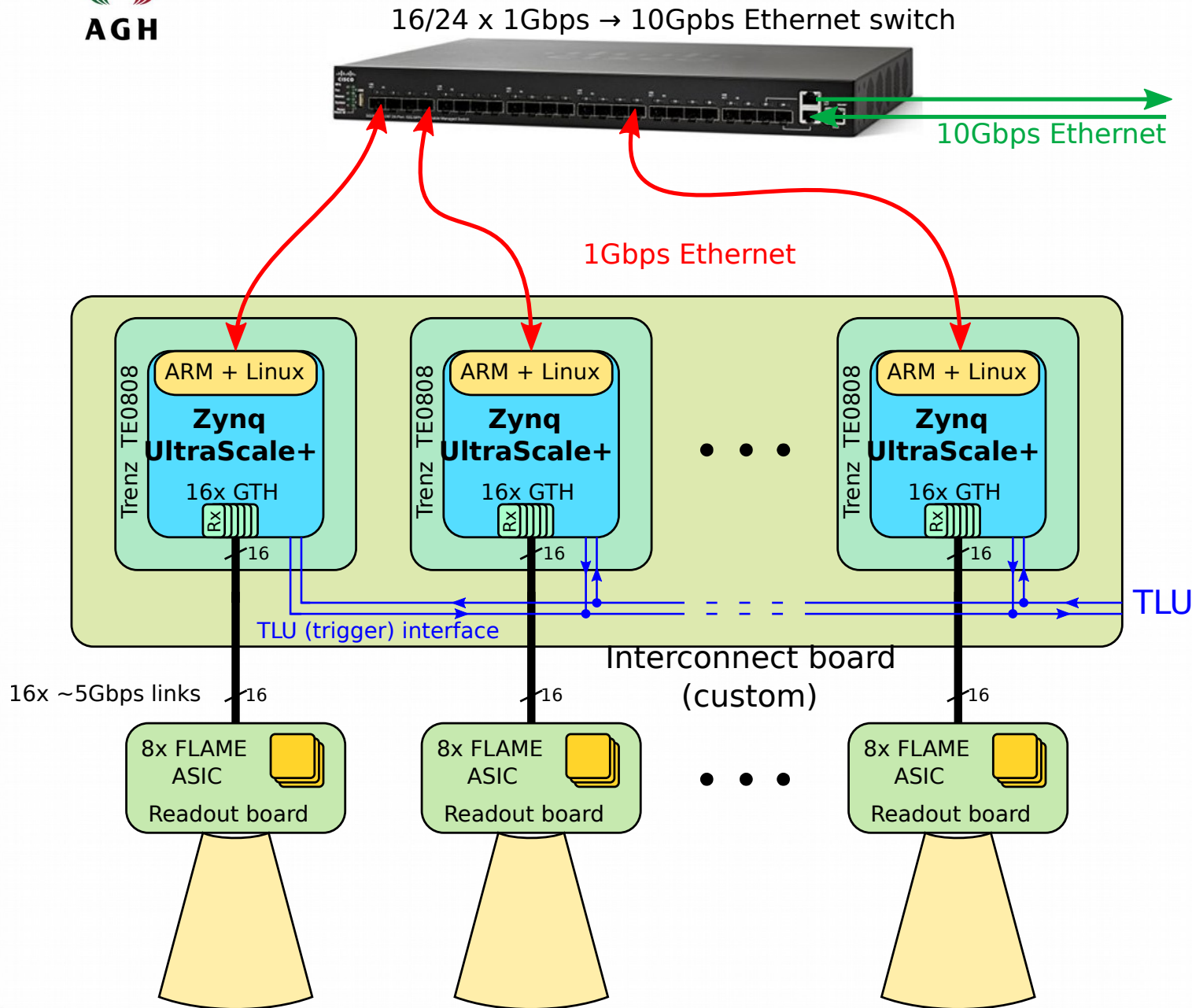
Zynq UltraScale+ MPSoC Product Tables and Product Selection Guide



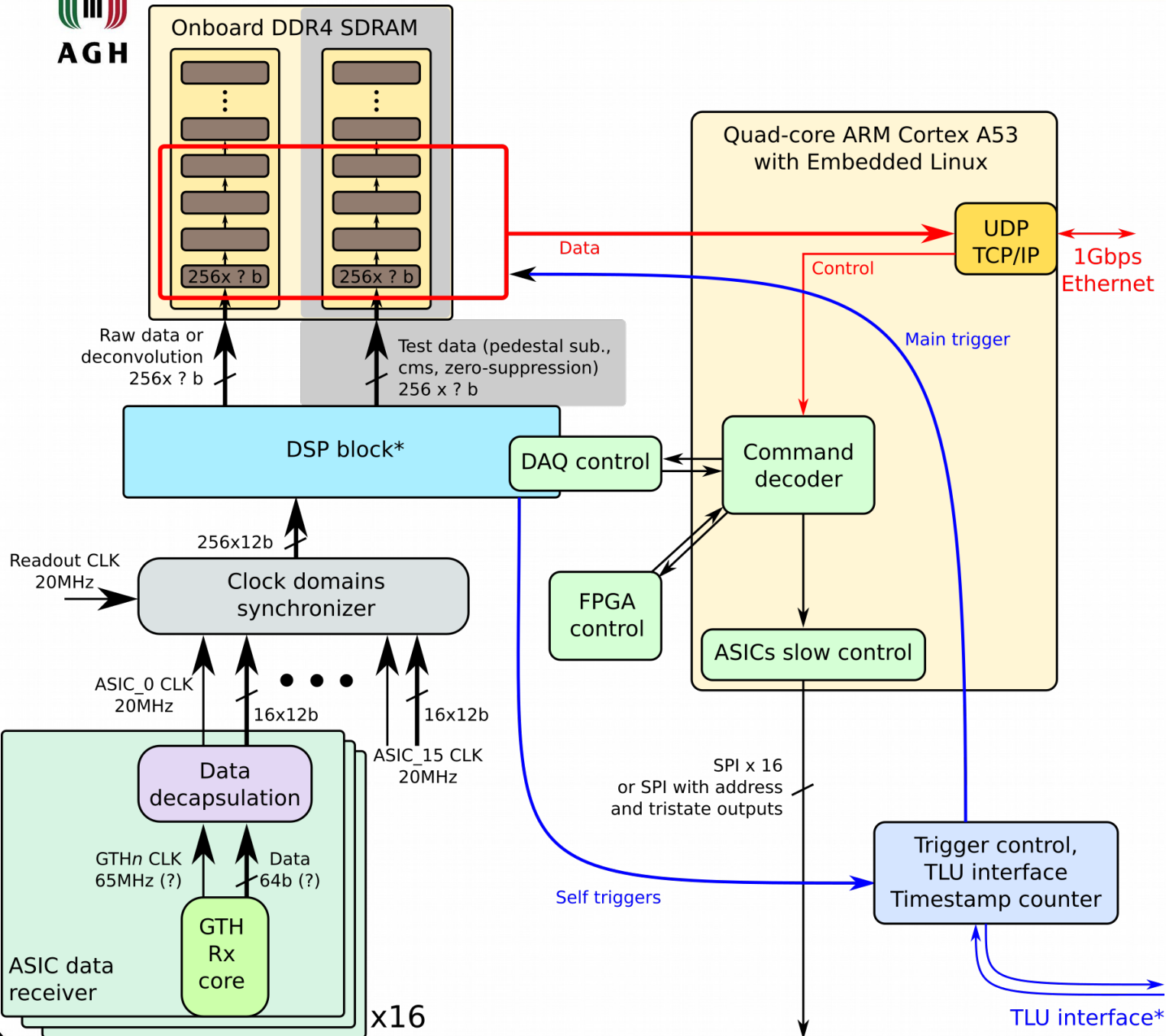
Zynq UltraScale+ Family

Zynq® UltraScale+™ MPSoCs: EG Devices

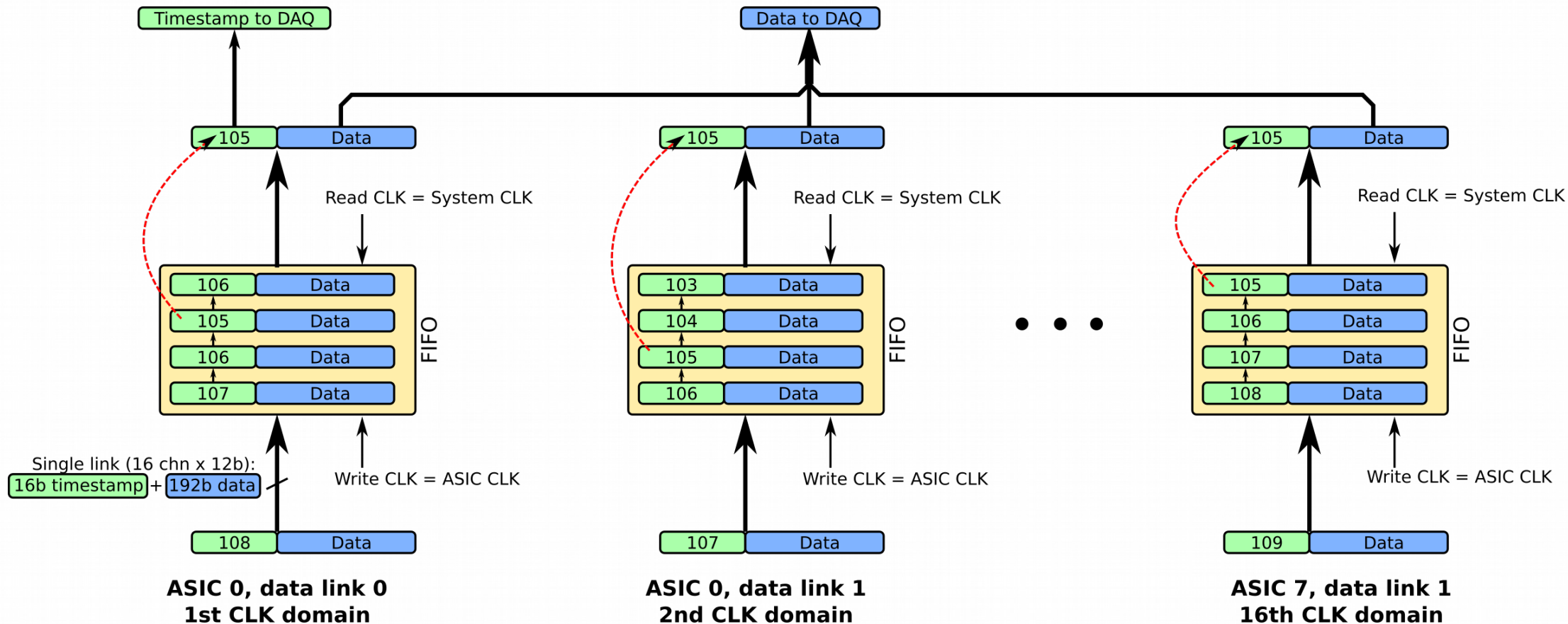
		Device Name ⁽¹⁾	ZU2EG	ZU3EG	ZU4EG	ZU5EG	ZU6EG	ZU7EG	ZU9EG	ZU11EG	ZU15EG	ZU17EG	ZU19EG
Processing System (PS)	Application	Processor Core	Quad-core ARM® Cortex™-A53 MPCore™ up to 1.5GHz										
	Processor Unit	Memory w/ECC	L1 Cache 32KB I/ D per core, L2 Cache 1MB, on-chip Memory 256KB										
	Real-Time	Processor Core	Dual-core ARM Cortex-R5 MPCore™ up to 600MHz										
	Processor Unit	Memory w/ECC	L1 Cache 32KB I/ D per core, Tightly Coupled Memory 128KB per core										
	Graphic & Video	Graphics Processing Unit	Mali™-400 MP2 up to 667MHz										
	Acceleration	Memory	L2 Cache 64KB										
	External Memory	Dynamic Memory Interface	x32/x64: DDR4, LPDDR4, DDR3, DDR3L, LPDDR3 with ECC										
		Static Memory Interfaces	NAND, 2x Quad-SPI										
	Connectivity	High-Speed Connectivity	PCIe® Gen2 x4, 2x USB3.0, SATA 3.0, DisplayPort, 4x Tri-mode Gigabit Ethernet										
		General Connectivity	2xUSB 2.0, 2x SD/SDIO, 2x UART, 2x CAN 2.0B, 2x I2C, 2x SPI, 4x 32b GPIO										
Integrated Block Functionality	Power Management	Full / Low / PL / Battery Power Domains											
	Security	RSA, AES, and SHA											
	AMS - System Monitor	10-bit, 1MSPS – Temperature and Voltage Monitor											
PS to PL Interface		12 x 32/64/128b AXI Ports											
Programmable Logic (PL)	Programmable Functionality	System Logic Cells (K)	103	154	192	256	469	504	600	653	747	926	1,143
		CLB Flip-Flops (K)	94	141	176	234	429	461	548	597	682	847	1,045
		CLB LUTs (K)	47	71	88	117	215	230	274	299	341	423	523
	Memory	Max. Distributed RAM (Mb)	1.2	1.8	2.6	3.5	6.9	6.2	8.8	9.1	11.3	8.0	9.8
		Total Block RAM (Mb)	5.3	7.6	4.5	5.1	25.1	11.0	32.1	21.1	26.2	28.0	34.6
		UltraRAM (Mb)	-	-	13.5	18.0	-	27.0	-	22.5	31.5	28.7	36.0
	Clocking	Clock Management Tiles (CMTs)	3	3	4	4	4	8	4	8	4	11	11
	Integrated IP	DSP Slices	240	360	728	1,248	1,973	1,728	2,520	2,928	3,528	1,590	1,968
		PCI Express® Gen 3x16	-	-	2	2	-	2	-	4	-	4	5
		150G Interlaken	-	-	-	-	-	-	-	1	-	2	4
		100G Ethernet MAC/PCS w/RS-FEC	-	-	-	-	-	-	-	2	-	2	4
	Transceivers	AMS - System Monitor	1	1	1	1	1	1	1	1	1	1	1
		GTH 16.3Gb/s Transceivers	-	-	16	16	24	24	24	32	24	44	44
		GTY 32.75Gb/s Transceivers	-	-	-	-	-	-	-	16	-	28	28
Speed Grades	Extended ⁽²⁾	-1 -2 -2L		-1 -2 -2L -3					-1 -2 -2L -3				
	Industrial						-1 -1L -2						
							1070	1189		1605	EUR		



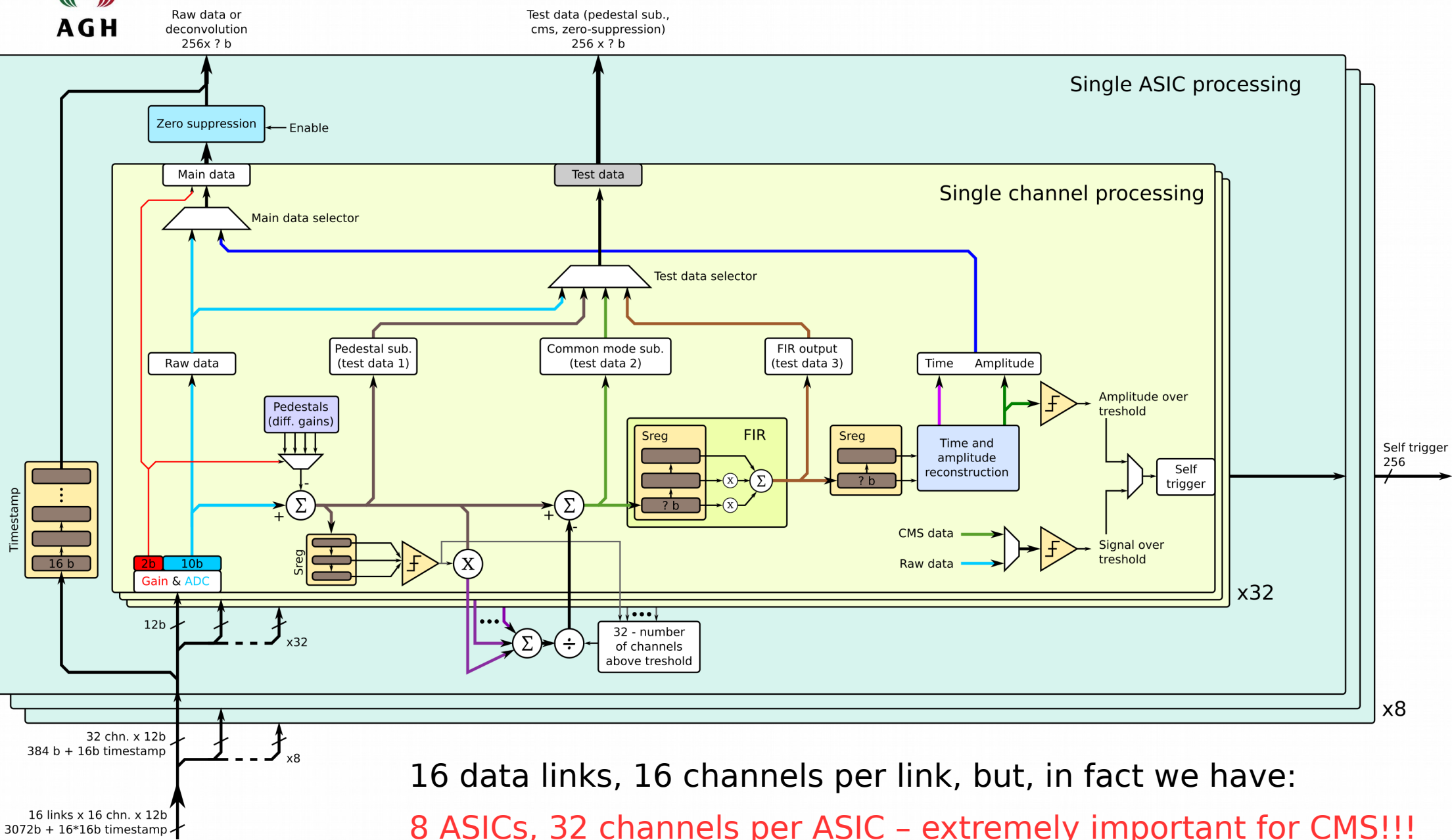
- 8 FLAME ASICs / plane = 256 channels = 16 data links (2 links per ASIC)
- New Trenz Electronic modules with Zynq UltraScale+ FPGAs available from the end of this year.
- 16 GTH transceivers / FPGA = 1 FPGA / plane
- Integrated ARM + embedded linux = 1Gbps Ethernet “for free”
- Simple Ethernet switch used as data concentrator
- One drawback - TLU (trigger) interface and timestamp synchronization not so straightforward...



- Data from 8 ASICs (16 links) received by GTH transceivers and decapsulated
- Clock domains (16 receivers = 16 domains) synchronized with main CLK (see next)
- DSP (pedestal, cm subtraction, FIR, deconvolution, ZS)
- Data feed by FPGA logic into onboard RAM
- On trigger data read out by ARM and send out through 1 Gbps ethernet
- DAQ and ASICs slow control - by software on ARM (linux)



- Clock domains synchronizer combines samples with the same timestamp and synchronizes clock phases
- If one ASIC / data link is dead, the synchronizer should build incomplete sample and inform DAQ that one data channel is missing and should not be processed, especially in cms procedure



16 data links, 16 channels per link, but, in fact we have:
8 ASICs, 32 channels per ASIC – extremely important for CMS!!!

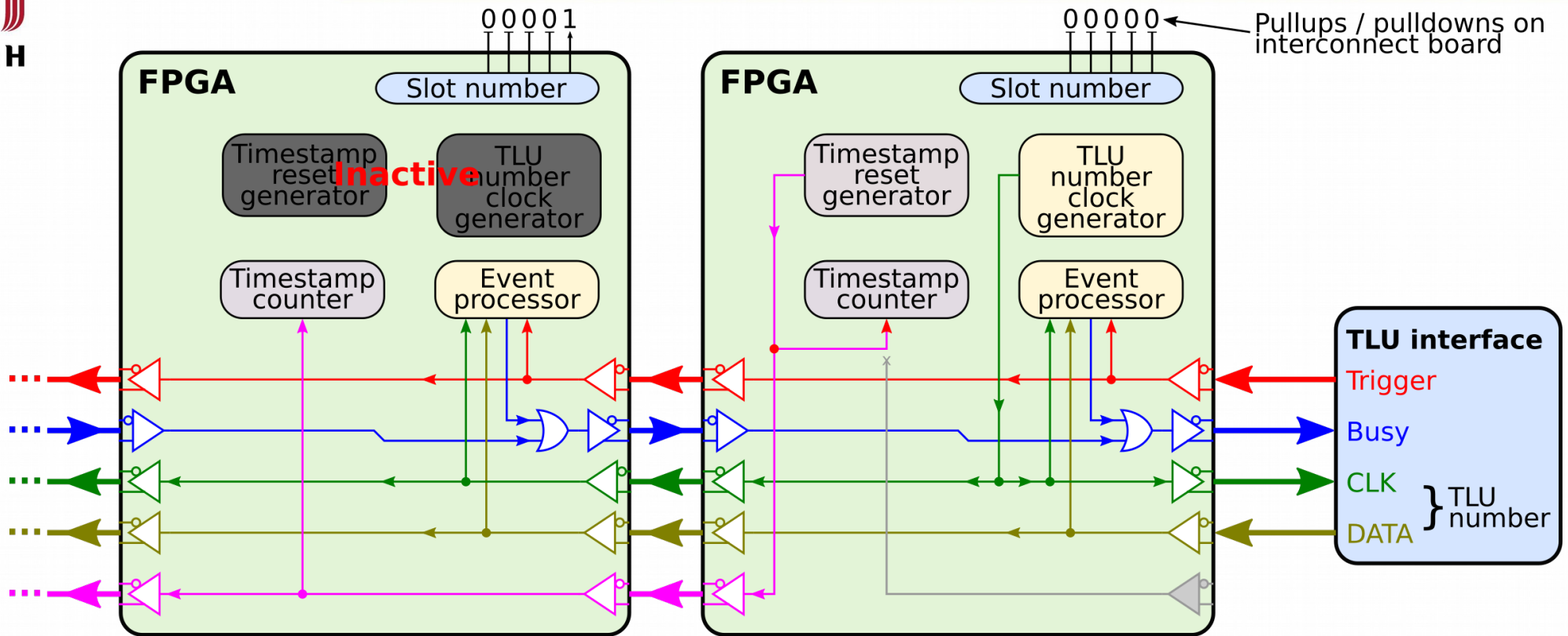
Python-based software simulating whole ASIC and DAQ chain is almost done:

- **FLAME data generator is done**
 - Generates “real” data – pedestal with noise, randomly distributed CM disturbances and randomly generated CR-RC pulses
- **DAQ based on real binary fixed point arithmetic (with overflow supervision) is done**
 - Pedestal subtraction
 - Signal detection for CMS (this is a little tricky...)
 - Common mode subtraction (CMS)
 - FIR (deconvolution filter)
 - Signal detection in FIR output samples for amplitude reconstruction (gives also zero suppression)
 - Amplitude and time reconstruction
- **Verification class – work in progress**
- **Simulations of complete chain to determinate required fixed point resolution – not done**
- We should schedule additional meeting for DSP details...

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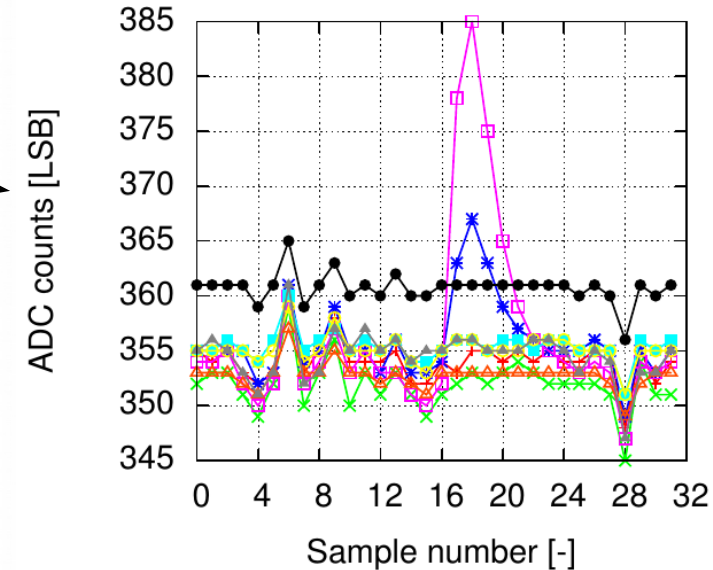
203 > #####
204 > # Common mode subtraction procedure
205 > #
206 > # Arguments:
207 > # event in bfr
208 > # detected_pulses: list of samples recognized as signal (pulse), generated by "detect_pulses"
209 > # method
210 > # threshold : ONLY FOR VERIFICATION PURPOSES
211 > # Allows to detect common mode disturbances by checking if common mode
212 > # calculated for given sample is above "threshold".
213 > # * if None, the verification cm_injections list is not build
214 > #
215 > # Returns tuple (event, cm_injections) where
216 > # * cm_injections is a list of detected common mode disturbances build as follows:
217 > # [ (cm disturbance occurrence sample number, disturbance amplitude [float ADC codes]) ,
218 > # (next cm disturbance occurrence sample number, next disturbance amplitude [float ADC codes]),
219 > # ...
220 > # ]
221 > #
222 > #####
223 > def cms(self, event, detected_pulses, threshold=None):
224 >     cms_ave=self.new_bfpr(0.,self.cms_average_PREC)
225 >     chns=len(event)
226 >     cm_injections=[]
227 >
228 >     for smp in range(len(event[0])):
229 >         cms_ave.assign(0.)
230 >         n=0
231 >         for chn in range(chns):
232 >             if not smp in detected_pulses[chn]:
233 >                 cms_ave=cms_ave+event[chn][smp]
234 >                 n+=1
235 >             if n:
236 >                 cms_ave=cms_ave/n
237 >                 for chn in range(chns):
238 >                     event[chn][smp]=event[chn][smp]-cms_ave
239 >                     if not threshold is None:
240 >                         if cms_ave>threshold:
241 >                             cm_injections.append((smp,float(cms_ave)))
242 >
243 >     return (event,cm_injections)
244 >
245 > #####
246 > # Pulse detector
247 > #
248 > # Arguments:
249 > # event in bfr
250 > # threshold: tuple/list [threshold value, samples above threshold]
251 > #
252 > # This method searches for samples belonging to pulse by finding if all samples in any
253 > # of threshold[1]-length sequences are above threshold[0]
254 > # threshold[1]-length sequences are build around tested sample in order to cover all
255 > # possible combinations: from [sample no. - threshold[1] + 1 : sample no.] to
256 > # [sample no. : sample no. + threshold[1] - 1]
257 > #
258 > # Returns pulses tuple build as follows:
259 > # [ [chn0 sample above threshold index, chn0 next sample above threshold index, ...],
260 > # [chn1 sample above threshold index, chn1 next sample above threshold index, ...],
261 > # ...
262 > # [chnChns sample above threshold index, chnChns next sample above threshold index, ...]
263 > # ]
264 > #####
265 > def detect_pulses(self, event, threshold):
266 >     smps=len(event[0])
267 >     chns=len(event)
268 >     pulses=[]
269 >     smp_shift=threshold[1]-1
270 >
271 >     # In all above comments, the smp_shift=2 assumption is done!
272 >     for chn in range(chns):
273 >         pulses.append([])
274 >         # Compare each sample with threshold and build "compare" list with boolean values
275 >         # and add 2 False values at beginning and 2 at the end of the list to avoid boundary problem (smp+1...)
276 >         compare=[False]*smp_shift+[x>threshold[0] for x in event[chn]]+[False]*smp_shift
277 >
278 >         # Check all samples; range 2->smps+2 because 2 dummy samples are added on the beginnig
279 >         for smp in range(smp_shift,smps+smp_shift):
280 >             signal=False
281 >             # Check id sample is above threshold
282 >             if compare[smp]:
283 >                 # If so, check combinations: (smp-2 & smp-1 & smp) | (smp-1 & smp & smp+1) | (smp & smp+1 & smp+2)
284 >                 for j in range(-smp_shift,1):
285 >                     signal|=all(compare[smp+j]:smp+j+smp_shift+1)
286 >                 if signal:
287 >                     pulses[chn].append(smp-smp_shift)

```



- Since LVDS/CML standard is used for TLU signals, FPGA inputs cannot be connected in parallel. Solution: pass (wire) through each FPGA with conversion CML → single ended (inside FPGA) → CML
- Trigger and TLU number data passed to all FPGAs; busy ORed inside each FPGA with busy signal from previous
- FPGA in slot **0** responsible for generating the TLU number read clock → distributed to TLU and all other FPGAs
- FPGA in slot **0** responsible for generating timestamp reset signal (on demand from DAQ control software)
- Timestamp reset and TLU number clock generators inactive in all FPGAs with slot number **!= 0**
- Slots numbered by combination of pullups / pulldowns on interconnect board
- Exactly the same firmware in each FPGA - behavior determined only by slot number → minibboards with FPGA can be replaced / exchanged between slots without any firmware change

- Old DAQ scheme - 16/32 raw ADC samples (10b) per channel per each trigger (event)
- New DAQ (with amplitude reconstruction) - two 16b(?) values (time, amplitude) per channels per event.
Even less with ZS, dependently on occupancy



- Assuming 32 raw samples / event, 12b data (10b ADC + 2b gain):
 - $32 \times 12b \times 256 \text{ channels} = 12 \text{ kB / event / plane for raw data}$
 - $1 \times 32b \times 256 \text{ channels} = 1 \text{ kB / event /plane for reconstruction data}$
- Assuming 400 Mbps as reasonable bandwidth for 1Gbps ethernet, we have
 - $\sim 4k \text{ events per second}$ or $< 49k \text{ events per second}$ for single plane
- Assuming 16 planes and 4 Gbps bandwidth for 10Gbps link:
 - $\sim 2.5k \text{ events per second}$ or $\sim 30.5k \text{ events per second}$

Ethernet is not a bottleneck for DAQ

The storage is a main bottleneck for DAQ

- Assuming 16 planes and 4 Gbps bandwidth for 10Gbps link:
 - ~2.5k events per second or ~30.5k events per second
- Single HDD (WD Red) – average write bandwidth ~100 MBps:
 - ~500 events per second or ~6.2k events per second – 5 times slower!
- RAID 5 (3x WD Red) – average write bandwidth ~300 Mbps:
 - ~1.5k events per second or <19k events per second – still 1.7 times slower!

But there is one more limit...

- Assuming one week long testbeam, data collected only for 70% of the time
 - For raw data @1k events/s we will need 81 TB!!! of storage capacity
 - For reconstructed amplitudes @1k events/s only **7 TB** is needed...

We cannot work with raw data!

- DAQ will be fully and easily scalable:
 - the interconnect board can be modular: e.g. PCB for 4 FPGA modules that can be connected to another interconnect board maintaining the TLU interface and synchronization chain
 - We don't have to fill all FPGA slots, the system will work even with one FPGA
 - The 16-port ethernet switch seems to have the best price to capabilities ratio; if more than 16 detector layers will be used, a second switch would be the best choice

Questions

- 1) Are we going to use this DAQ only for AIDA2020 (one testbeam), or also for future developments?
- 2) How many layers are we going to use in testbeam next year?
 - a) Especially – how many FPGA modules should we buy now?
- 3) How many layers are we going to use in the future – 16 / 30 / 40?

Firmware

- FLAME data receiver (*IFJ Krakow* → ???)
 - Done, but on different FPGA – have to be ported to UltraScale+ Zynq
- Clock domains synchroniser (*JINR Dubna*)
 - Probably done
- DSP (*JINR Dubna*)
 - Not started yet, waiting for software DSP model (*by me*)
- Control, TLU interface, timestamp synchronization, etc. (???)
 - Not started yet
- ARM linux, ethernet & software (???)
 - Not started yet

Hardware (PCBs)

- FLAME testboard, readout (detector plane) PCB (*AGH Kraków*)
 - Not started yet, waiting for final FLAME padding
- FPGA interconnection board PCB (*AGH Kraków*)
 - Not started yet, waiting for tests on Trenz Electronic module and some decisions...

- New DAQ scheme proposed based on Zynq UltraScale+ modules
- Some firmware details still have to be fixed
- We should decide how to share the work on firmware
 - 1) **Who can help - Krakow / Dubna / somebody else?**
- We should buy more TE0808 modules on the beginning of next year
 - 2) **How many layers are we going to use in testbeam next year and how many in the future?**
 - 3) **Can anyone buy a few more modules?**